AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A cross-over structure of first and second separate elongate conductive interconnects, comprising:

a first elongate conductive interconnect;

a second elongate conductive interconnect comprising:

a first conductive portion separate from the first elongate conductive interconnect;

a second conductive portion separate from the first elongate conductive interconnect and the first conductive portion; and

a third electro-deposited metal portion interconnecting the first and second conductive portions; and

first insulating material between the first elongate conductive interconnect and the third electro-deposited metal portion of the second elongate interconnect; and

a substrate, wherein:

the first insulating material and the third electro-deposited metal portion are positioned between the substrate and the first elongate conductive interconnect; and

the second elongate conductive interconnect extends the length of the cross-over structure.

2. (Original) A cross-over as claimed in claim 1, wherein the first and second elongate conductive interconnects are formed from electro-deposited metal.

3-5. (Cancelled).

6. (Previously Presented) A cross-over as claimed in claim 1, having a first layer and a second layer, wherein the first elongate conductive interconnect occupies at least the first layer and the second elongate conductive interconnect occupies the first and second layers.

7. (Original) A cross-over as claimed in claim 6, wherein the first layer comprises at least a portion of the first elongate conductive interconnect, the first conductive portion, the second conductive portion and second insulating material between the first metal portion and the first elongate conductive interconnect and between the second metal portion and the first elongate conductive interconnect and the second layer comprises first insulating material adjacent at least a portion of the first elongate conductive interconnect, and the third interconnecting metal portion.

8-10. (Cancelled).

11. (Previously Presented) A cross-over as claimed in claim 1, wherein the first elongate conductive layer comprises electro-deposited metal.

12. (Previously Presented) A cross-over as claimed in claim 1, wherein the first elongate conductive interconnect is formed from the same material as the first and second portions of the second conductive interconnect.

13. (Cancelled).

14. (Previously Presented) A cross-over as claimed in claim 1, wherein the first and second conductive portions comprises electro-deposited metal and each extends in a second direction at an angle to the first direction of elongation of the first elongate conductive member.

15-16. (Cancelled).

17. (Previously Presented) A cross-over as claimed in claim 1, wherein the third metal portion bridges the first insulating material.

18. (Original) A cross-over as claimed in claim 17, wherein the third metal portion is encapsulated and underlies the first insulating material.

19. (Previously Presented) A cross-over as claimed in claim 1 having a substantially planar surface including substantially planar surface portions of the first and second conductive interconnects.

20. (Previously Presented) A cross-over as claimed in claim 1 further comprising a substrate and insulating adhesive material between the substrate and the first and second conductive interconnects.

21-22. (Cancelled).

23. (Previously Presented) An active-matrix display, comprising a plurality of cross-overs as claimed in claim 1.

24. (Currently Amended) A method of crossing a first elongate conductive interconnect and a separate second elongate conductive interconnect in an integrated circuit, comprising:

a) forming a first elongate conductive interconnect ;

b) forming a first conductive portion separate from the first elongate conductive interconnect;

c) forming a second conductive portion separate from the first elongate conductive interconnect;

d) depositing first insulating material over at least a portion of the first elongate conductive interconnect; and

e) electro-depositing metal to form a third electro-deposited metal portion extending over the first insulating material to interconnect the first and second conductive portions and form the second elongate conductive interconnect; and

f) transferring the structure formed in steps a) to e) to a substrate, wherein the second elongate conductive interconnect extends the length of the integrated circuit structure.

25. (Cancelled).

26. (Previously Presented) A method as claimed in claim 24, wherein step d) involves the selective retention of photo-curable material.

27. (Previously Presented) A method as claimed in any one of claims 24, wherein, in step a), the first elongate conductive interconnect is formed by electro-deposition of metal;

in step b), the first conductive portion of the second elongate conductive interconnect is formed by electro-deposition of metal; and

in step c), the second conductive portion of the second elongate conductive interconnect is formed by electro-deposition of metal.

28-29. (Cancelled).

30. (Previously Presented) A method as claimed in claim 24, wherein step a), b) and c) occur at the same time during a single metal electro-deposition process.

31. (Original) A method as claimed in 30, wherein the metal electro-deposition process involves masked electrolytic deposition.

32. (Original) A method as claimed in claim 31, wherein the mask is second insulator material that is incorporated into the final structure.

33-35. (Cancelled).

36. (Previously Presented) A cross-over formed by the method of claim 24.

37. (Currently Amended) A cross-over structure of first and second conductive means, comprising:

first conductive means;

second conductive means comprising:

a first conductive portion separate from the first conductive means;

a second conductive portion separate from the first conductive means and the first conductive portion; and

a third electro-deposited metal portion interconnecting the first and second conductive portions; and

first insulating means for insulating the first conductive means from the second conductive means wherein the first insulating means directly contacts the third electro-deposited metal portion and the second conductive means extends lengthwise across the cross-over structure.

38-39. (Cancelled).